CST200N03G N-Ch 30V Fast Switching MOSFETs

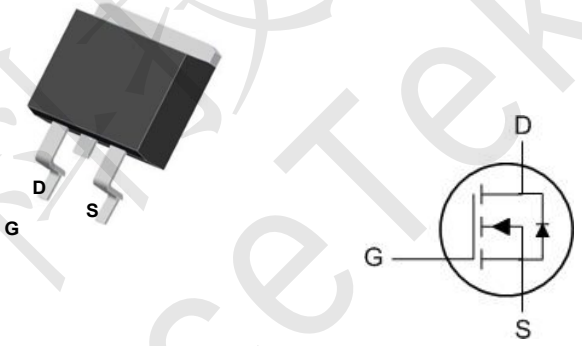
★ 100% EAS Guaranteed
★ Green Device Available
★ Super Low Gate Charge
★ Excellent CdV/dt effect decline
★ Advanced high cell density Trench technology

CST200N03G Product Summary

Green

BVDSS	RDSON	ID
30V	1.6mΩ	200A

CST200N03G TO263 Pin Configuration



CST200N03G Description

The CST200N03G is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.
The CST200N03G meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

CST200N03G Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	200	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	80	A
I_{DM}	Pulsed Drain Current[2]	450	A
EAS	Single Pulse Avalanche Energy[3]	580	mJ
I_{AS}	Avalanche Current	60	A
P_D@T_C=25℃	Total Power Dissipation[4]	87	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

CST200N03G Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	2.1	℃/W

TEL: +86-0755-27595155 27595165
FAX: +86-0755-27594792
WEB:Http://www.ChipSourceTek.com
E-mail: Sales@ChipSourceTek.com Tony.Wang@ChipSourceTek.com

CST200N03G Electrical characteristic (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV_{DSS}	Drain to source breakdown voltage	V_{GS}=0V, I_D=250uA	30			V
ΔBV_{DSS} / ΔT_J	Breakdown voltage temperature coefficient	I_D=250uA, referenced to 25°C		0.02		V/°C
I_{DSS}	Drain to source leakage current	V_{DS}=30V, V_{GS}=0V			1	uA
		V_{DS}=24V, T_J=125°C			50	uA
I_{GSS}	Gate to source leakage current, forward	V_{GS}=20V, V_{DS}=0V			100	nA
	Gate to source leakage current, reverse	V_{GS}=-20V, V_{DS}=0V			-100	nA
On characteristics						
$V_{GS(TH)}$	Gate threshold voltage	V_{DS}=V_{GS}, I_D=250uA	1.2		2.4	V
$R_{DS(ON)}$	Drain to source on state resistance	V_{GS}=4.5V, I_D=30A,T_J=25°C		2.2	4.8	mΩ
		V_{GS}=10V, I_D=30A,T_J=25°C		1.6	2.9	mΩ
		V_{GS}=10V, I_D=30A,T_J=125°C		2.5		mΩ
G_{fs}	Forward transconductance	V_{DS}=5V, I_D=30A		73		S
Dynamic characteristics						
C_{iss}	Input capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		6272		pF
C_{oss}	Output capacitance			1022		
C_{rss}	Reverse transfer capacitance			718		
$t_{d(on)}$	Turn on delay time	V_{DS}=15V, I_D=30A, R_G=4.7Ω, V_{GS}=10V (note 4,5)		20		ns
t_r	Rising time			58		
$t_{d(off)}$	Turn off delay time			158		
t_f	Fall time			77		
Q_g	Total gate charge	V_{DS}=24V, V_{GS}=10V, I_D=30A , I_G=5mA (note 4,5)		143		nC
Q_{gs}	Gate-source charge			17		
Q_{gd}	Gate-drain charge			43		
R_g	Gate resistance	V_{DS}=0V, Scan F mode		4.2		Ω

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			200	A
I_{SM}	Pulsed source current				440	A
V_{SD}	Diode forward voltage drop.	I_S=45A, V_{GS}=0V			1.4	V
t_{rr}	Reverse recovery time	I_S=30A, V_{GS}=0V, dI_F/dt=100A/us		26		ns
Q_{rr}	Reverse recovery charge			10		nC

※. Notes
1. Repeatitive rating : pulse width limited by junction temperature.
2. L =0.5mH, I_{AS} =48A, V_{DD}=30V, R_G=25Ω, Starting T_J = 25°C
3. I_{SD} ≤30A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Staring T_J =25°C
4. Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%.
5.

TEL: +86-0755-27595155 27595165
FAX: +86-0755-27594792
WEB:Http://www.ChipSourceTek.com
E-mail: Sales@ChipSourceTek.com Tony.Wang@ChipSourceTek.com

N- Channel Typical Characteristics

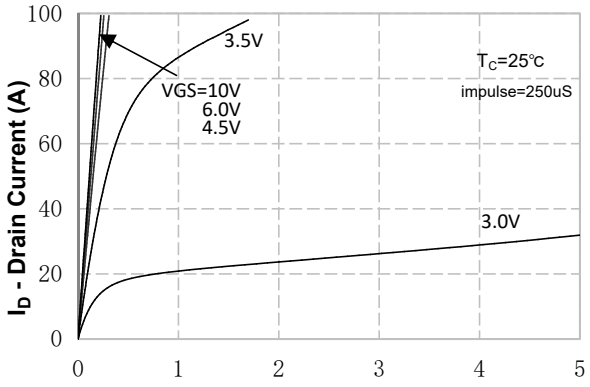


Figure 1. On-Region Characteristics

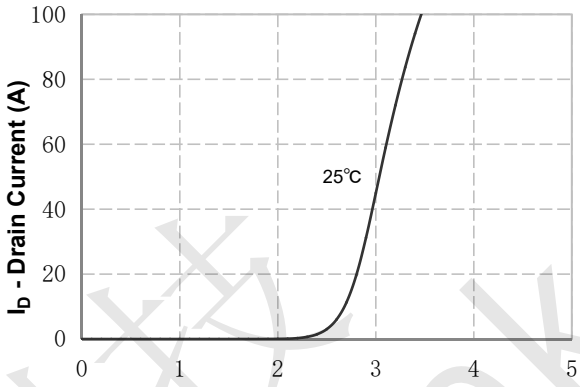


Figure 2. Transfer Characteristics

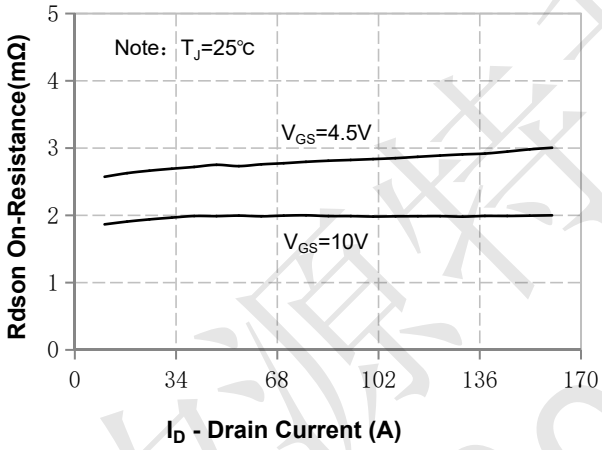


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

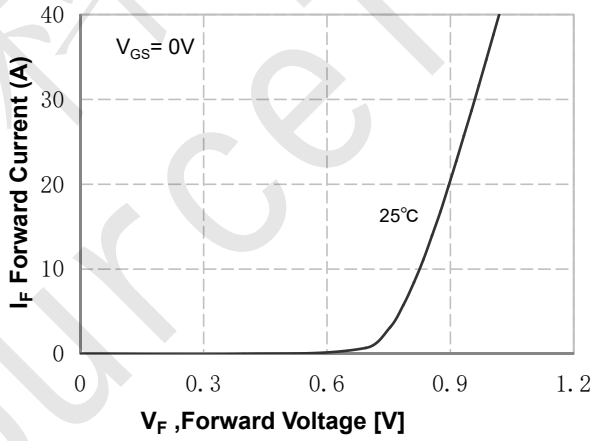


Figure 4. Body Diode Forward Voltage Variation vs Source Current

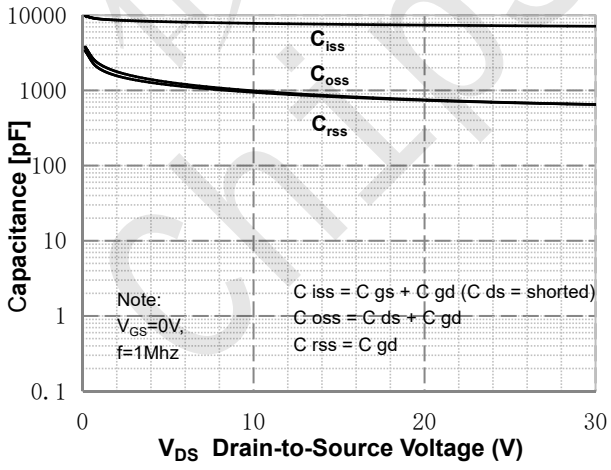


Figure 5. Capacitance Characteristics

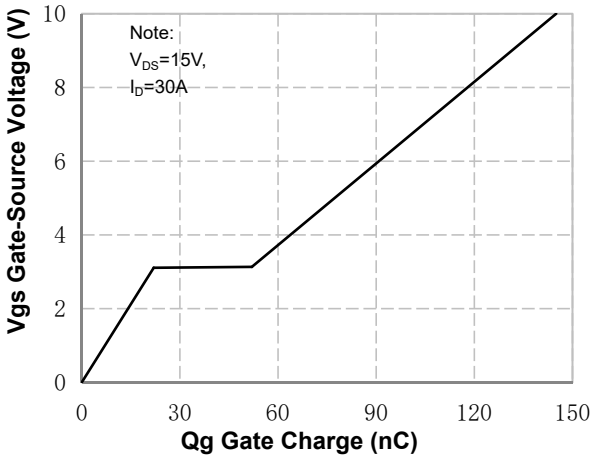


Figure 6. Gate Charge Characteristics

N- Channel Typical Characteristics (Continued)

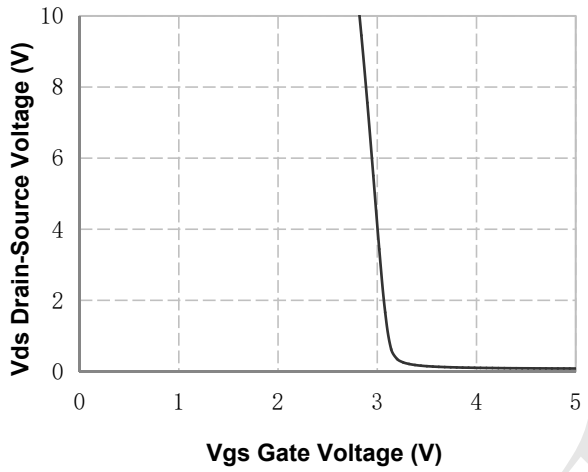


Figure 7. Vds Drain-Source Voltage vs Gate Voltage

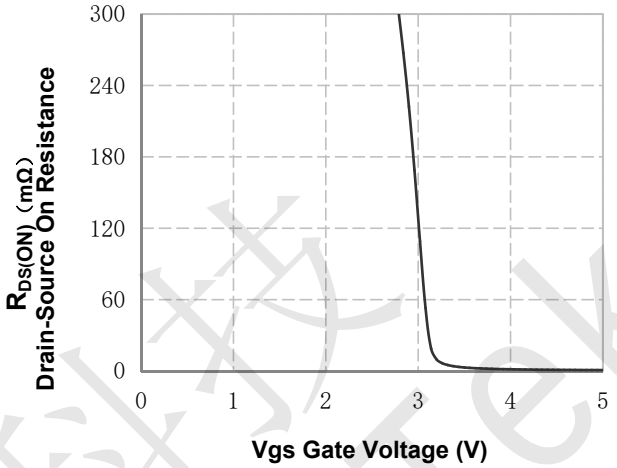


Figure 8. On-Resistance vs Gate Voltage

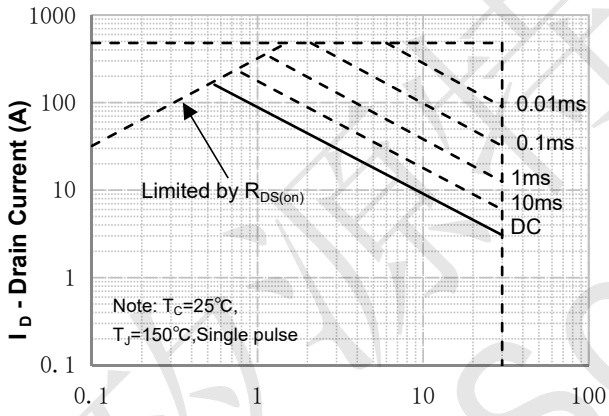


Figure 9. Maximum Safe Operating Area

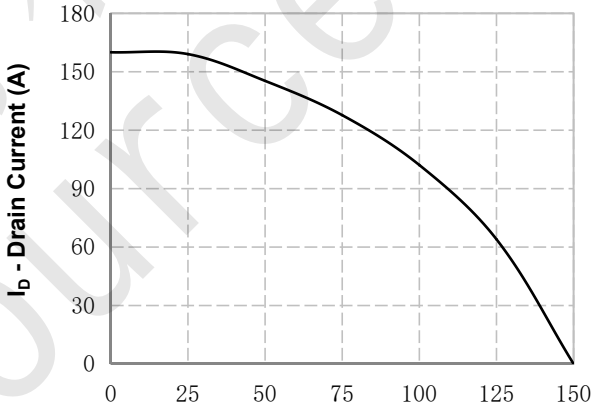


Figure 10. Maximum Continuous Drain Current vs Temperature

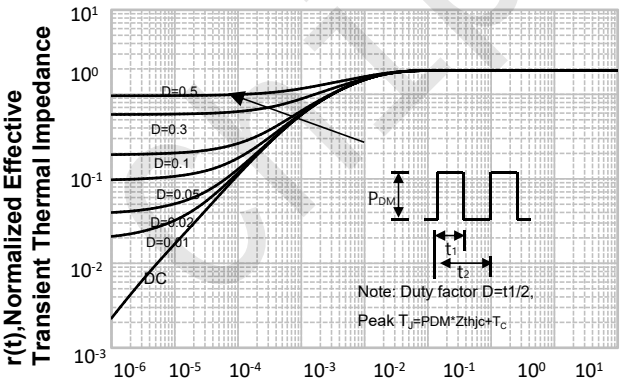
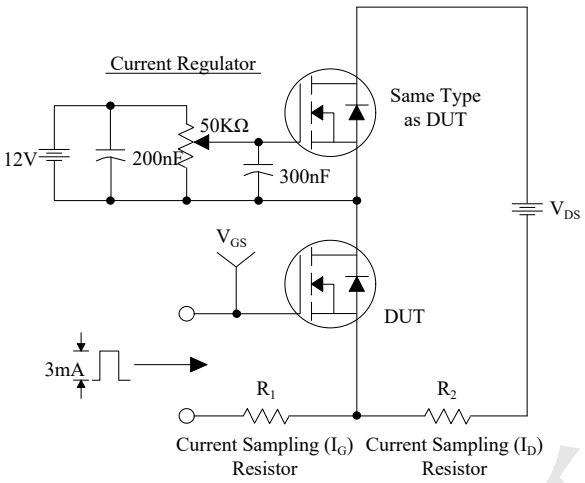
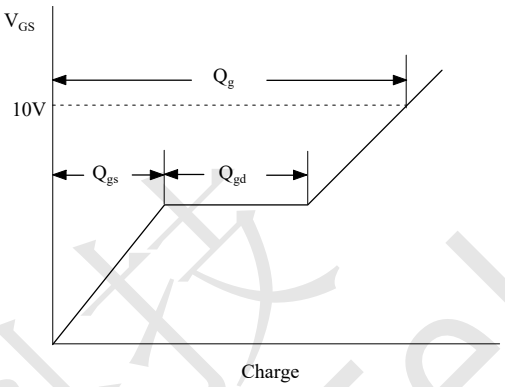


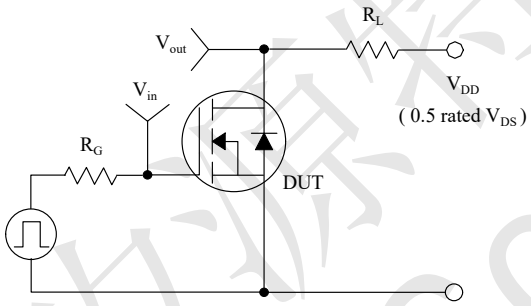
Figure 11. Transient Thermal Response Curve

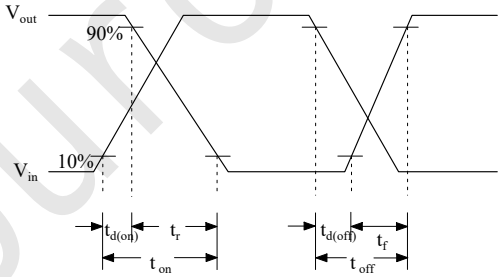
Gate Charge Test Circuit & Waveform



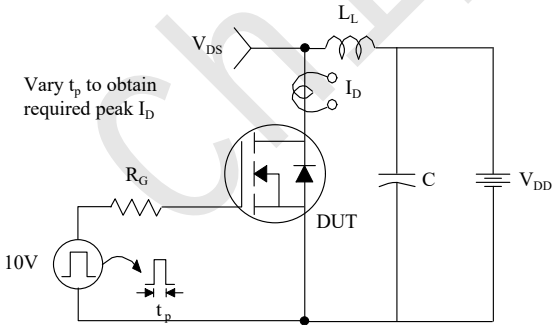


Resistive Switching Test Circuit & Waveforms

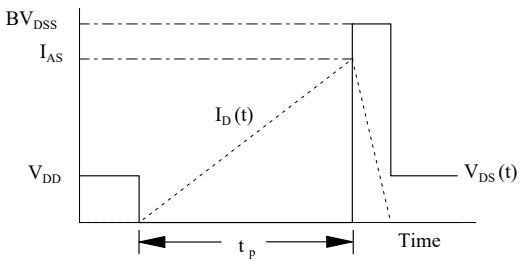




Unclamped Inductive Switching Test Circuit & Waveforms

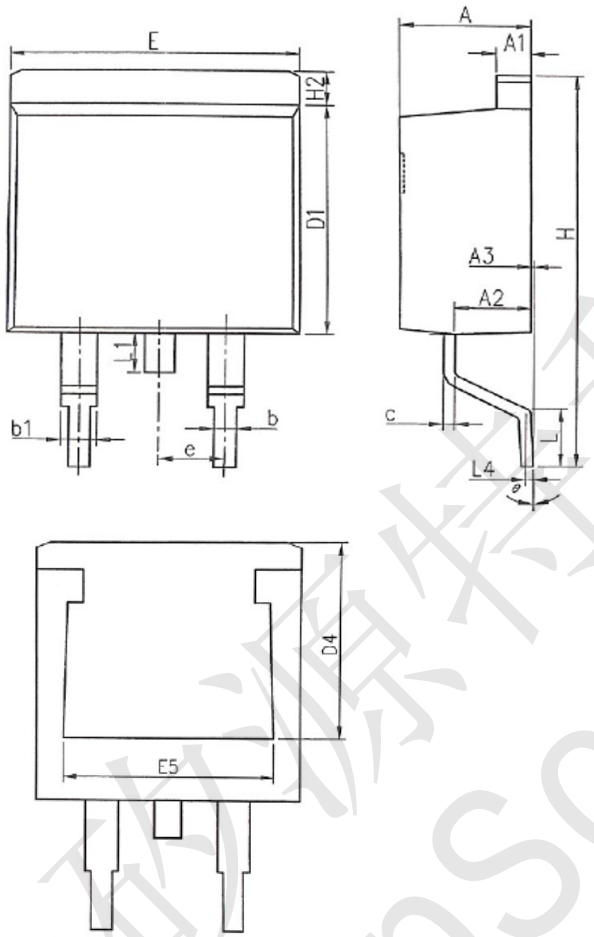


$$E_{AS} = \frac{1}{2} L_L I_{AS}^2$$



TEL: +86-0755-27595155 27595165
FAX: +86-0755-27594792
WEB:Http://www.ChipSourceTek.com
E-mail: Sales@ChipSourceTek.com Tony.Wang@ChipSourceTek.com

CST200N03G Mechanical Dimensions for TO-263



COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	4.37	4.89
A1	1.17	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.28	0.60
D1	8.45	9.30
D4	6.60	-
E	9.80	10.40
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.80
L1	-	1.75
L4	0.254BSC	
θ	0°	9°

TEL: +86-0755-27595155 27595165
FAX: +86-0755-27594792
WEB:Http://www.ChipSourceTek.com
E-mail: Sales@ChipSourceTek.com Tony.Wang@ChipSourceTek.com